

MSKSEMI

SEMICONDUCTOR



ESD



TVS



TSS



MOV

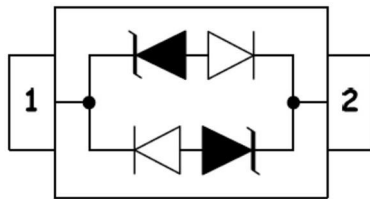


GDT



PLED

Product data sheet



SOD-323

FEATURES

- ◇ Transient protection for high-speed data lines
IEC 61000-4-2 (ESD) $\pm 30\text{kV}$ (Contact)
 $\pm 30\text{kV}$ (Air)
IEC 61000-4-4 (EFT) 40A (5/50 ns)
- ◇ Protects one I/O line (bidirectional)
- ◇ Working voltages : 36V
- ◇ Low clamping voltage
- ◇ Low leakage current
- ◇ Response time is $< 1\text{ ns}$

MACHANICAL DATA

- ◇ SOD-323 package
- ◇ Flammability Rating: UL 94V-0
- ◇ Packaging: Tape and Reel
- ◇ High temperature soldering guaranteed:
 $260^{\circ}\text{C}/10\text{s}$
- ◇ Reel size: 7 inch
- ◇ MSL1

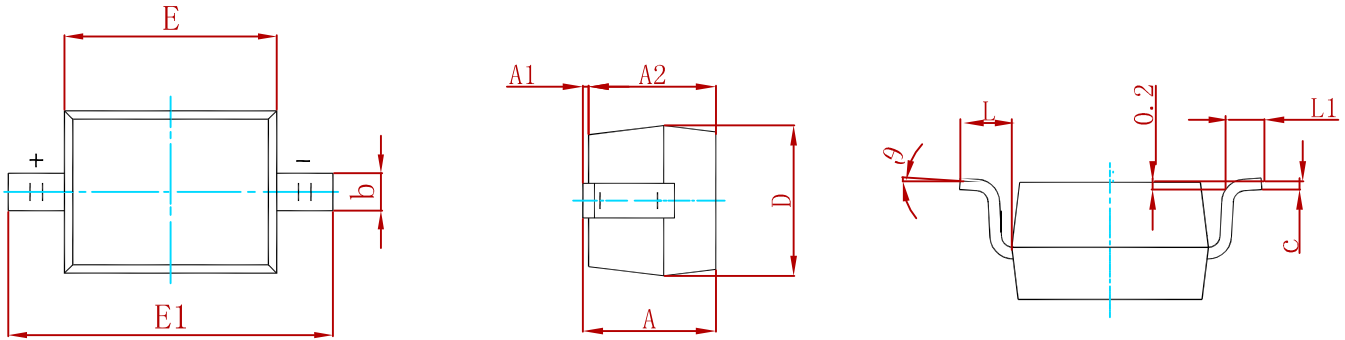
APPLICATIONS

- ◇ Cell Phone Handsets and Accessories
- ◇ Microprocessor based equipment
- ◇ Personal Digital Assistants (PDA's)
- ◇ Notebooks, Desktops, and Servers
- ◇ Portable Instrumentation
- ◇ Peripherals
- ◇ USB Interface

ABSOLUTE MAXIMUM RATING			
Symbol	Parameter	Value	Units
V_{ESD}	ESD per IEC 61000-4-2 (Contact)	±30	kV
	ESD per IEC 61000-4-2 (Air)	±30	
P_{PP}	Peak Pulse Power (8/20µs)	350	W
T_{OPT}	Operating Temperature	-55/+150	°C
T_{STG}	Storage Temperature	-55/+150	°C
T_L	Lead Soldering Temperature	260	°C

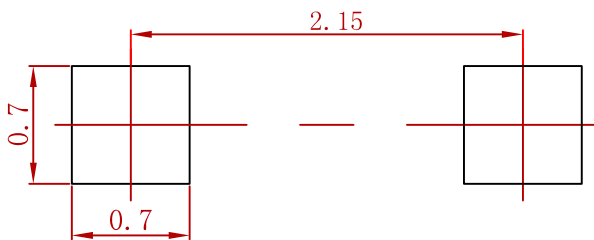
ELECTRICAL CHARACTERISTICS ($T_{amb}=25^{\circ}C$)									
P/N	V_{RWM} (V)	$V_B@1mA$ (V)	$V_C@1A$ (V)	$V_C@I_{pp}$ (V)		$V_C@I_{pp}$ (V)		I_R (µA)	C_T (pF)
	Max	Min	Max	Max	I_{pp} (A)	Max	I_{pp} (A)	Max	Typ.
GBLC36CI-MS	36.0	40.0	60.0	65.0	2	75.0	4.5	1	0.8

PACKAGE MECHANICAL DATA



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A		1.000		0.039
A1	0.000	0.100	0.000	0.004
A2	0.800	0.900	0.031	0.035
b	0.250	0.350	0.010	0.014
c	0.080	0.150	0.003	0.006
D	1.200	1.400	0.047	0.055
E	1.600	1.800	0.063	0.071
E1	2.550	2.750	0.100	0.108
L	0.475 REF.		0.019 REF.	
L1	0.250	0.400	0.010	0.016
θ	0°	8°	0°	8°

Suggested Pad Layout



Note:
 1. Controlling dimension: in millimeters.
 2. General tolerance: $\pm 0.05\text{mm}$.
 3. The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
GBLC36CI-MS	SOD-323	3000

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